

so that the electrode of the electronic component is electrically connected with the electrode of the circuit board.

2. An electronic component mounting method as
5 claimed in claim 1, wherein, before mounting the electronic component on the board by aligning in position the electrode of the electronic component with the electrode (5) of the circuit board (4) with interposition of the anisotropic conductive layer after the formation of the
10 bump,

a tip of the formed bump is shaped so as to prevent collapse of a neck portion of the bump by once pressurizing the bump with a load of not greater than 20 gf.

3. An electronic component mounting method as
15 claimed in claim 1 or 2, wherein

the insulating resin (6m) of the anisotropic conductive layer is an insulative thermosetting epoxy resin, and an amount of the inorganic filler mixed with this insulative thermosetting epoxy resin is 5 to 90 wt% of the
20 insulative thermosetting epoxy resin.

4. An electronic component mounting method as claimed in any one of claims 1 through 3, wherein

the insulating resin (6m) of the anisotropic conductive layer is in a liquid form when applied to the
25 board, and after semi-solidifying the resin by hardening

the liquid of the applied insulating resin with the board placed in a furnace (503) or by pressurizing the liquid of the applied insulating resin by means of a heated tool (78) after the application to the board, the electronic component is mounted on the board.

5. An electronic component mounting method comprising:

forming a ball (96, 96a) at a tip of a metal wire (95) by an electric spark similarly to wire bonding and forming a gold bump (3, 103) by thermocompression-bonding the formed ball to an electrode (2) of an electronic component (1) with supersonic waves by means of a capillary (93, 193);

mounting the electronic component on a circuit board (4) by aligning in position the electrode of the electronic component with an electrode (5) of the board with interposition of an anisotropic conductive layer (10) in which an insulating resin mixed with an inorganic filler is mixed with a conductive particle (10a) without leveling the formed bump;

subsequently metallically bonding the gold bump to the electrode of the board with supersonic waves applied while shaping a tip so as to prevent collapse of a neck portion of the gold bump with a load applied from an upper surface side of the electronic component by means of a tool

(8); and

subsequently bonding the electronic component to the circuit board by hardening the insulating resin of the anisotropic conductive layer interposed between the electronic component and the circuit board while correcting warp of the board and crushing the bump with a pressure force of not smaller than 20 gf per bump applied to the electronic component against the circuit board and heat applied from the upper surface side of the electronic component or heat applied from the board side or heat applied from both the electronic component side and the board side, so that the electrode of the electronic component is electrically connected with the electrode of the circuit board.

6. An electronic component mounting method as claimed in any one of claims 1 through 5, wherein the electronic component (1) has a plurality of electrodes (2), a solid anisotropic conductive film sheet (10) that has a configurational dimension smaller than an outline dimension (OL) defined by joining the plurality of electrodes (2) of the electronic component (1) is stuck as the anisotropic conductive layer to the circuit board (4) before the positional alignment and thereafter subjected to the positional alignment, and at the bonding time, the insulating resin interposed between the electronic